

REMARKS

Reconsideration of the application in view of the above amendments and the following remarks is respectfully requested.

The Examiner rejects Claim 1 under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. The Examiner rejects the term "high" in claim 1 is a relative term which renders the claim indefinite. Claim 1 has been cancelled without prejudice.

The Examiner rejects Claims 1-4 under 35 U.S.C. 102(e) as being anticipated by Sakawaki. Claims 1-4 have been cancelled without prejudice and replaced by new Claims 5-25.

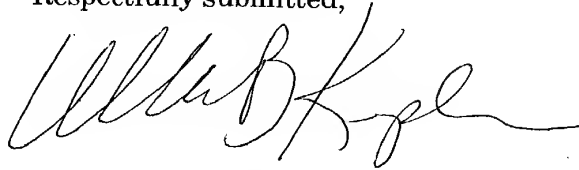
Applicants do not agree that Sakawaki anticipates the present invention or renders it obvious. In Sakawaki, the material is placed on the center of the wafer while the wafer is rotated at a relatively low speed of 50 to 150 rpm. Then, the wafer is rotated at a higher speed of 1000 to 6000 rpm in order to the spread this material. Sakawaki raises at top of column 5 the possibility of rotating the wafer at a third yet higher speed. In Sakawaki, the nozzle 11 is moved while supplying the coating solution to the center of the substrate.

In sharp contrast, the present invention relies upon a different regime of operating speeds to reduce the amount of material applied to the wafer substantially. In the present invention, for an eight inch wafer the amount of resistance material is reduced from 8cc to 2cc, the material required for a six inch wafer it is reduced from 3cc to 1cc, and the material required for a 5 inch wafer is reduced from a 3cc to 0.7cc. Clearly, the present invention provides at least a two-thirds savings in material, and thus provides a technical advantage over the reference cited by the Examiner. Claim 5 has been added in order to specifically recite the regime of the present invention and thus clearly distinguishes this claim and the dependent claims from Sakawaki.



Accordingly, applicants believe the application, as amended, is in condition for allowance, and such action is respectfully requested.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read 'William B. Kempler', written in dark ink.

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